

Amendments to the Specification:

Please amend the Abstract as follows:

Abstract

[Object]—A method for processing a substrate and an apparatus for processing a substrate are provided, where a substrate can be prevented from being damaged during conveyance of the substrate, including turning over of the substrate, and the apparatus for processing a substrate having this mechanism for conveying a substrate is miniaturized, so that the area for installment can be reduced.

[Means for Achieving Object] An apparatus for processing a substrate which divides divide a mother substrate into unit substrates. The apparatus is provided with a scribing portion 3-for drawing a scribe line on a mother substrate, a breaking portion 4-for breaking a mother substrate along the formed scribe line, and a portion for conveying a substrate 2-for conveying a mother substrate or a unit substrate at least between the above described respective portions, wherein portion for conveying a substrate 2-has a number of rotational supports 51-and 73-with a suction surface for sucking and holding each substrate from a main surface, rotational supports 51-and 73-have rotational axes 52-and 72,respectively, as well as meanssuction members for respectively sucking and rotating a substrate which rotates substrates around rotational axes 52-and 72, approximately simultaneously in a state where the substrates are sucked and held in such a manner that at least two main surfaces of each substrate are turned over in the upward and downward direction.